

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application:

Rajeev Joshi et al.

Serial No.: 10/618,113

Filed: July 11, 2003

For: WAFER-LEVEL CHIP SCALE
PACKAGEA AND METHOD FOR
FABRICATING AND USING THE SAME

Confirmation No. 8697

Group Art Unit: 2891

Examiner: David A Zarneke

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

REQUEST FOR RECONSIDERATION UNDER 37 C.F.R. § 1.111

In response to the Office Action dated May 15, 2007, Applicants request reconsideration of this application in light of the following remarks. Applicants have concurrently filed a petition for a one-month extension of time to extend the period of response to September 15, 2007.

Remarks begin on page 2 of this paper.